

Data Sheet Of Thermal Conductive Gel TSP-DC10X0 Series

Characteristic:

Thermal conductivity=1.0--6.0W/mk or customized .
 High thermal conductivity, low thermal resistance.
 Small Young modulus, Soft, relieving stress and shock mitigation.
 Can be dispensed through a variety of many automated processes.
 Good electrical insulation performance and temperature resistance.



Product's Description

The TSP-DC10X0 Series Two-component Thermal Gel Series is a thermal paste that can be cured at room temperature. After curing, it becomes a flexible rubber elastomer. It is suitable for electroonic/electrical fields with heat dissipation requirements, and is especially suitable for different components to share one large gap in the heat sink. It can automatically dispense to realize automatic operation.

Custom Service

1. Can choose dispensing or coating.
2. Can be filled according to customize requirements.

Product Models		TSPDC-1020	TSPDC-1030	TSPDC-1040	TSPDC-1050	TSPDC-1060	Unit	Test Standard
Color	Component A	Gray	White	White	Gray	White	---	Visual
	Component B	White	Gray	Yellow	Blue	Gray	---	Visual
	After Mixing	Gray	Offwhite	Buff	Offwhite	Offwhite	---	Visual
Density		3.35±0.2	≤2.5	2.0±0.2	1.8±0.2	1.8±0.2	g/cc	ASTM D792
Mixing Ratio		1:1	1:1	1:1	1:1	1:1	---	Mass ratio
Extrusion Rate		120@90Psi	180@90Psi	180@90Psi	180@90Psi	200@90Psi	g/min	---
Minimum Filling Gap		≤0.2	≤0.1	≤0.1	≤0.1	≤0.1	mm	---
UL Flammability Rating		V-0	V-0	V-0	V-0	V-0	---	UL-94
Continuous Use Temperature		-40±200	-40±200	-40±200	-40±200	-40±200	°C	EN334
After Vulcanization								
Thermal Conductivity		5	4	3	2	1	W/m-k	ASTM D5470
Thermal Resistance/1MM		≤0.25 @20psi	≤1.0 @20psi	≤1.5 @20psi	≤1.5 @20psi	≤2.0 @20psi	°Cin2/W	ASTM D5470
Electrical Properties								
Breakdown Voltage		≥5	≥10	≥10	≥10	≥10	kv/mm	ASTM D149
Volume Resistivity		≥10 ⁸	≥10 ¹²	≥10 ¹⁰	≥10 ¹⁰	≥10 ¹²	Ω.cm	ASTM D257

Typical Applications

1. Semiconductor blocks and various heat sinks, as well as various heat sinks for computers, tablets, and smartphones.
2. Used for LED lighting fixtures and luminous bodies.
3. High performance central processing unit and display card processor.
4. Large communication equipment and surrounding supporting equipment; Base station antenna device

Refrigerated or stored in a dark place, storage temperature: ≤ 25 °C, storage humidity: ≤ 70%

Packaging specifications: 30cc/55cc/300cc/2600cc

Issue By:

